IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

S/N 10/081,818

Jerome M. Eldridge et al.

Examiner: Tu-Tu Ho

Serial No.:

10/081,818

Group Art Unit: 2818

Filed:

February 20, 2002

Docket No.: 1303.045US1

Customer No.: 73115

Confirmation No.: 3148

Title:

ATOMIC LAYER DEPOSITION OF METAL OXIDE AND/OR LOW

ASYMMETRICAL TUNNEL BARRIER INTERPLOY INSULATORS

REQUEST TO APPLY PREVIOUSLY PAID ISSUE FEE

Mail Stop Issue Fee Commissioner for Patents P.O.Box 1450 Alexandria, VA 22313-1450

An issue fee for the above-identified application was previously paid on December 20, 2006. A petition under 37 CFR 1.313(c)(2) to withdraw the above-identified application from issue after payment of the issue fee was subsequently filed on February 5, 2007. Applicant received a decision, dated February 6, 2007, granting the petition to withdraw.

Applicant respectfully requests that the above-identified previously-paid issue fee be applied toward the fee required by the new Notice of Allowance dated August 8, 2008. The present issue fee has increased from the previously-paid issue fee. Transmitted herewith is authorization to charge Deposit Account 19-0743 in the amount of \$110.00 to cover the issue fee increase.

This request is being submitted together with the new Issue Fee Transmittal Form PTOL-85, as well as a copy of the above-identified decision granting the petition to withdraw. Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743. Please direct any inquiries to the undersigned attorney at (612) 349-9587.

Respectfully submitted,

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

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Minneapolis, MN 55402

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TBC:CMG:ker1

Date WW. '09

Timothy B. Clise Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 7th day of November, 2008.

IDATHLEEN E. ROTHROCK

Signature